

## Features

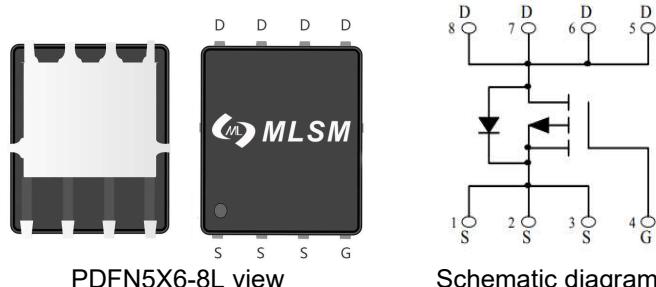
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

## Product Summary

$V_{DS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
-40V	14mΩ@-10V	-50A
	18mΩ@-4.5V	

## Application

- PWM applications
- Power management
- Load switch



Marking and pin assignment



Halogen-Free

## Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit
<b>Common Ratings (TC=25°C Unless Otherwise Noted)</b>			
$V_{DS}$	Drain-Source Breakdown Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$I_S$	Diode Continuous Forward Current	Tc=25°C -50	A
<b>Mounted on Large Heat Sink</b>			
$I_{DM}$	Pulse Drain Current Tested	Tc=25°C -232	A
$I_D$	Continuous Drain Current	Tc=25°C -50	A
$P_D$	Maximum Power Dissipation	Tc=25°C 50	W
$R_{\theta JA}$	Thermal Resistance Junction-to-Ambient	60	°C/W

## Ordering Information (Example)

Type	Package	Marking	Minimum Package(pcs)	Inner Box Quantity(pcs)	Outer Carton Quantity(pcs)	Delivery Mode
MC0E50AP	PDFN5X6-8L	MC0E50AP	5,000	10,000	70,000	13" reel

Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)</b>						
BV <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-40	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V	--	--	-1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-1.6	-2.5	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-25A	--	9	14	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	--	12	18	mΩ
<b>Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated)</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, f=1MHz	--	2980	--	pF
C <sub>OSS</sub>	Output Capacitance		--	380	--	pF
C <sub>RSS</sub>	Reverse Transfer Capacitance		--	300	--	pF
<b>Switching Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-20V, I <sub>D</sub> =-25A, V <sub>GS</sub> =-10V	--	75	--	nC
Q <sub>gs</sub>	Gate Source Charge		--	14	--	nC
Q <sub>gd</sub>	Gate Drain Charge		--	15	--	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-12V, I <sub>D</sub> =-25A, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω	--	10	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	17	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	38	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	25	--	nS
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Forward on voltage	T <sub>J</sub> =25°C, I <sub>S</sub> =-25A	--	--	-1.2	V

### Typical Operating Characteristics

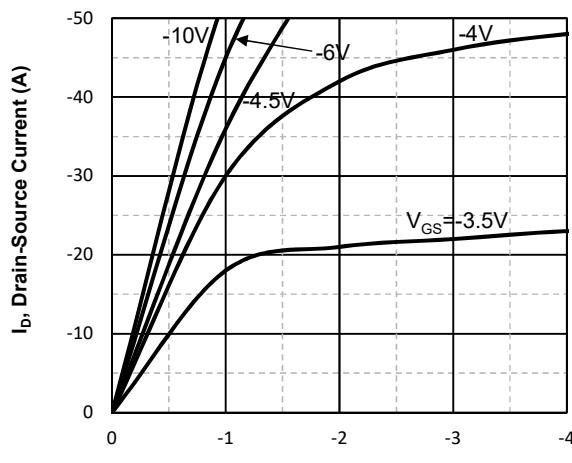


Fig1. Typical Output Characteristics

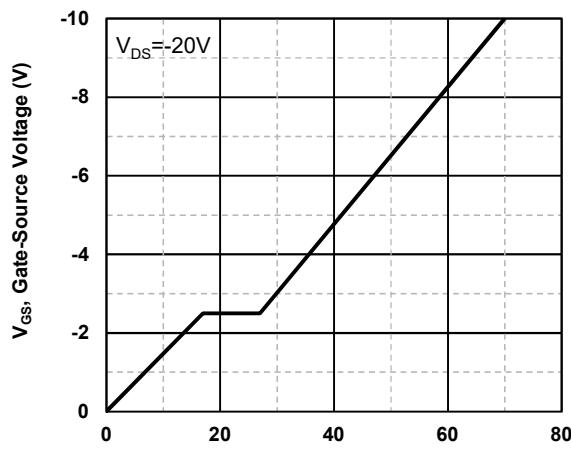


Fig2. Typical Gate Charge Vs.Gate-Source Voltage

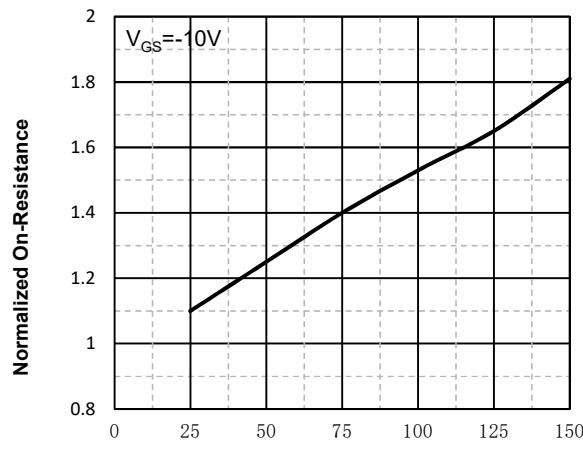


Fig3. Normalized On-Resistance Vs. Temperature

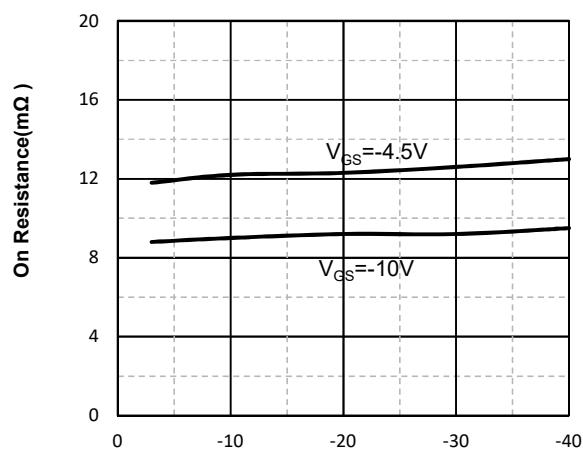


Fig4. On Resistance Vs. Drain-Source Current

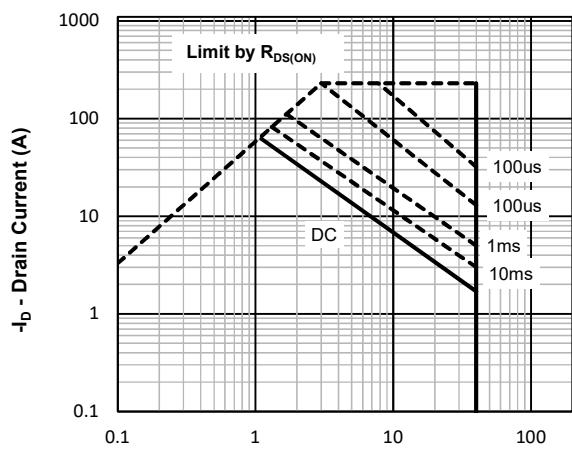


Fig5. Maximum Safe Operating Area

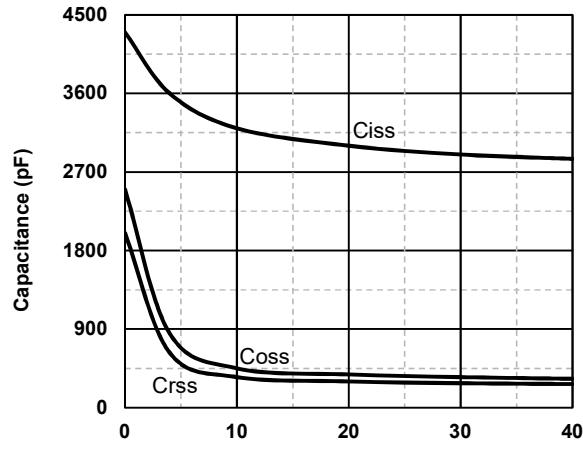
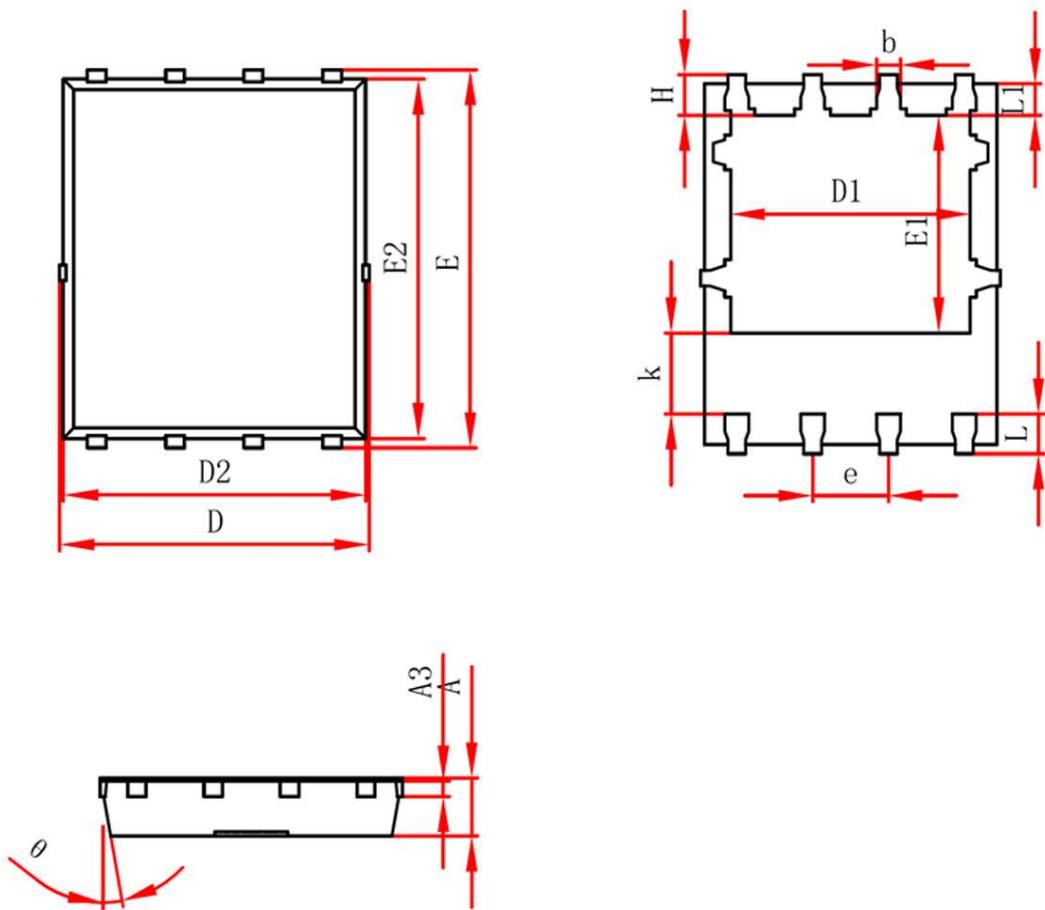


Fig6 Typical Capacitance Vs.Drain-Source Voltage

**PDFN5X6-8L Package information**


Symbol	Dimensions in Millimeters(mm)		Dimensions In Inches	
	Min	Max	Min	Max
A	0.950	1.050	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.950	5.050	0.196	0.200
E	5.950	6.050	0.235	0.239
D1	4.026	4.126	0.159	0.163
E1	3.510	3.610	0.139	0.143
D2	4.850	4.950	0.192	0.196
E2	5.700	5.800	0.225	0.229
k	1.190	1.390	0.047	0.055
b	0.300	0.400	0.012	0.016
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°